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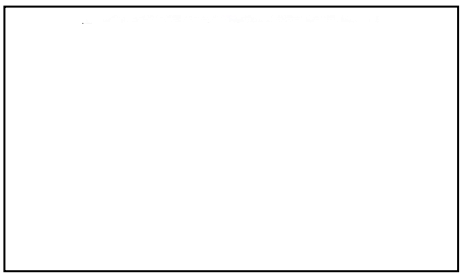
4.1 Handling Precautions 产品使用注意事项 20

1. Description 产品介绍

1.1General Description 产品描述



The Red source color devices are made with AlGaInP on Substrate Light Emitting Diode

红光 LED 由 AlGaInP 四种元素芯片激发而成

The Green source color devices are made with InGaN on Substrate Light Emitting Diode

绿光 LED 由 InGaN 三种元素芯片激发而成

The Blue source color devices are made with InGaN on Substrate Light Emitting Diode

蓝光 LED 由 InGaN 三种元素芯片激发而成

The White LED which was fabricated by using a blue chip and phosphors.

白光 LED，是由蓝光芯片激发荧光粉而形成。

The LED package dimension: 3.45mmX3.45mmX2.20mm.

产品尺寸：3.45mmX3.45mmX2.20mm。

1.2 Features 产品特征

Ceramics Package.

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.适用于所有的SMT组装和焊接工艺

Available on tape and reel.适用于载带及卷轴

Moisture sensitive level:Level1. 防潮等级：Level 1

RoHS compliant.满足RoHS要求

1.3Application 产品应用

Article color lamp, lamp belt. 彩色灯条、灯带

Landscape lighting　Trademark logo.景观照明，招牌字

Hotels,markets,offices,household and other indoor uses.酒店、商场、办公室、家用及其它室内用途

General use.其他应用

1.4Package Dimension 封装尺寸

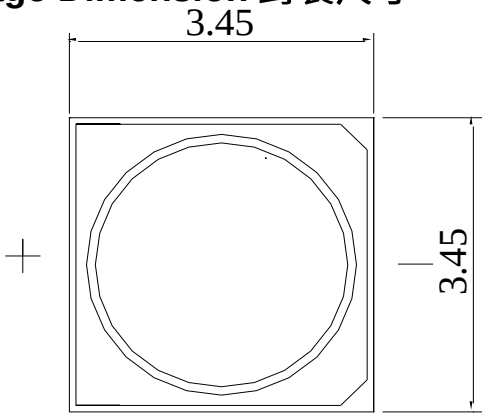


Fig.1-1 Top view 正面视图

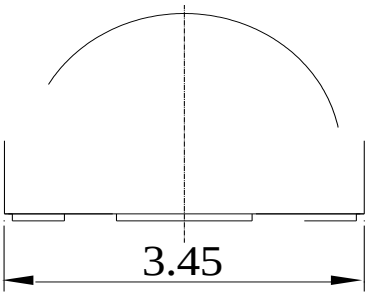


Fig.1-2 Side view 侧面视图

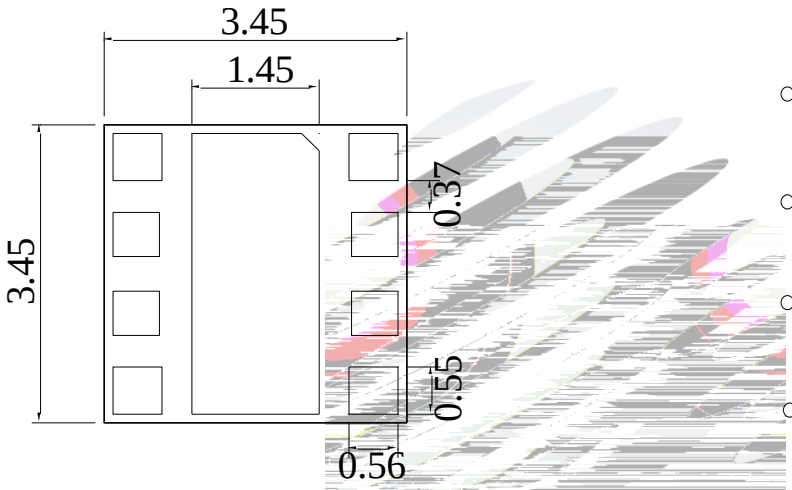


Fig.1-3 Bottom view 背面视图

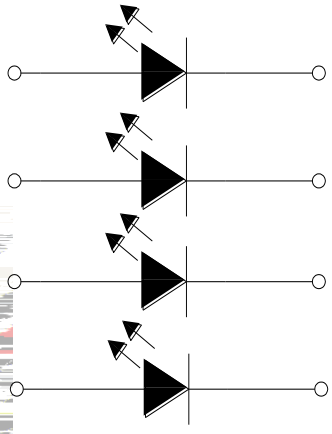


Fig.1-4 Polarity 极性

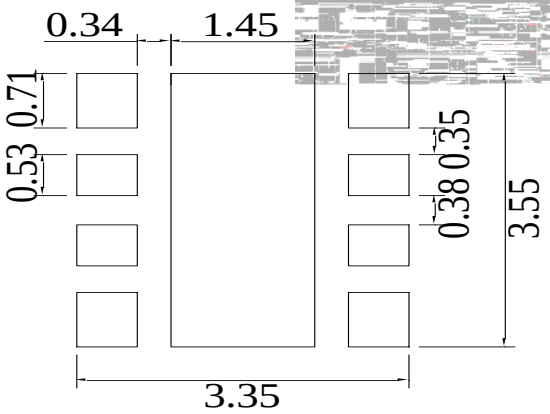


Fig.1-5 Soldering patterns 推荐焊盘

Notes 备注:

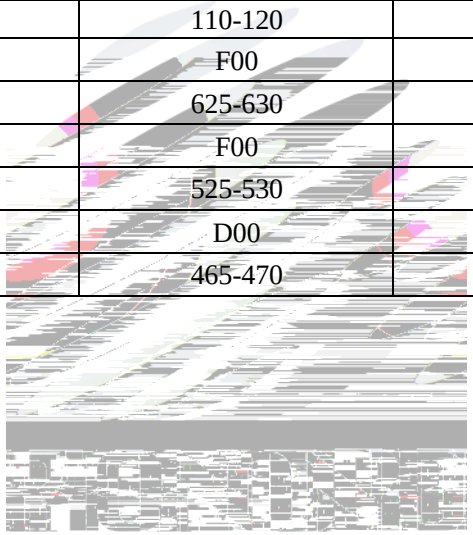
1. All dimensions units are millimeters. 所有尺寸标注单位为毫米

2. All dimensions tolerances are ±0.2mm unless otherwise noted.除特别标注外，所有尺寸公差为±0.2 毫米

1.5.1 Bin Range Of Forward Voltage and Luminous Intensity (IF=350mA)+e » > y j 6 BIN 93 $(IF=350mA)

Table 1-3

V_F V R	B0	C0	D0	
	1.8-2.0	2.0-2.2	2.2-2.4	
V_F V G&B&W	G0	H0	I0	
	2.8-3.0	3.0-3.2	3.2-3.4	
ÅR	FB7	FB8	FB9	
	50-60	60-70	70-80	
ÅG	FC2	FC3	FC4	FC5
	100-110	110-120	120-130	130-140
ÅB	FB4	FB5		
	20-30	30-40		
ÅW	FC2	FC3	FC4	FC5
	100-110	110-120	120-130	130-140
WD R (nm)	E00	F00		
	620-625	625-630		
WD G (nm)	E00	F00		
	520-525	525-530		
WD B (nm)	C00	D00	E00	
	460-465	465-470	470-475	



1.6 Typical optical characteristics curves [redacted]

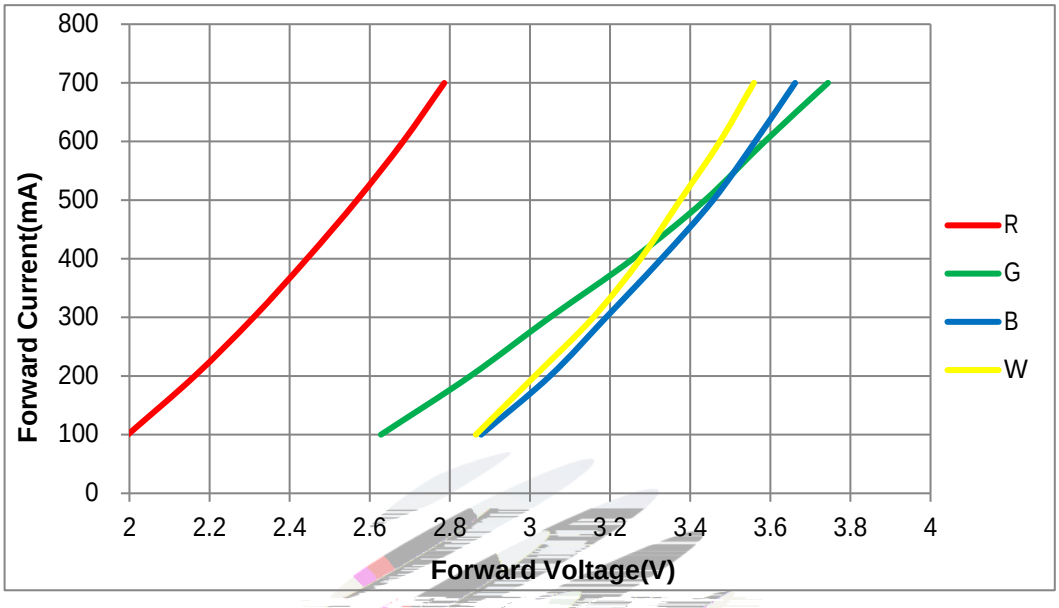


Fig 1-6 Forward Voltage Vs. Forward Current 伏安特性曲线

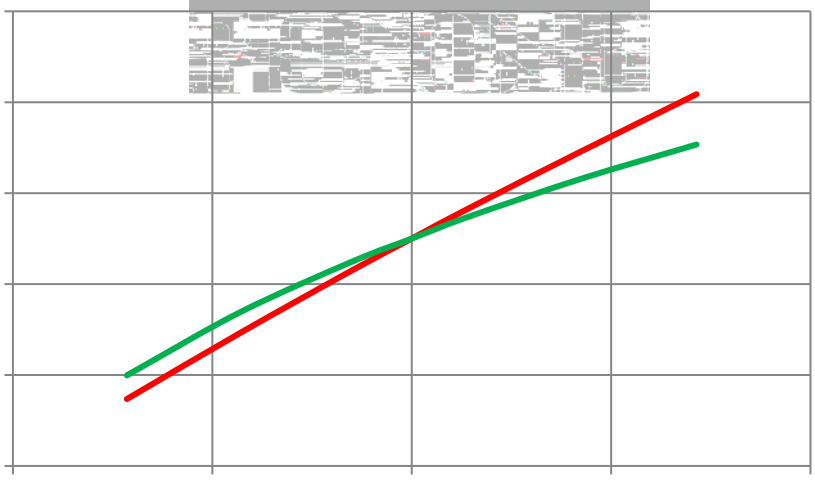


Fig.1-7 Forward Current Vs. Relative Intensity !“ A+e#q >-( ) y j(© W "4ï

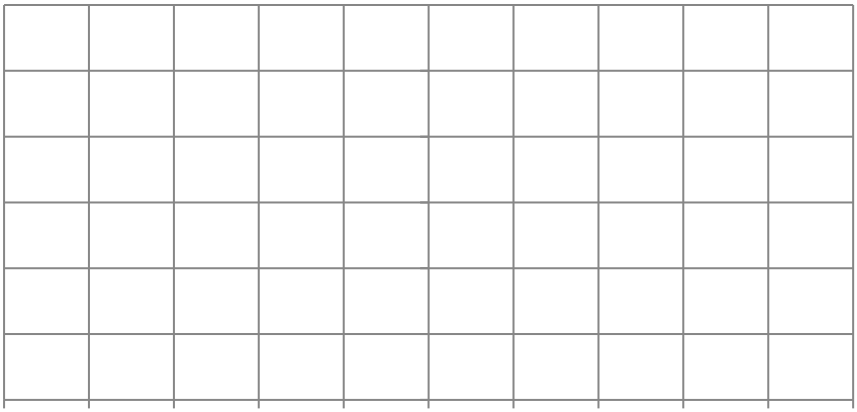


Fig 1-10 Radiation diagram辐射特性曲线

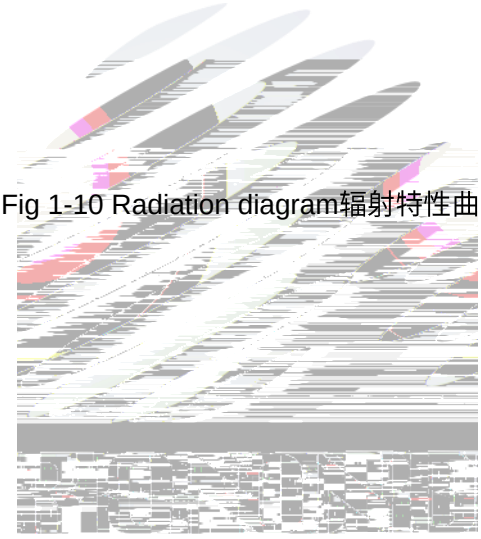


Fig 1-11 Spectrum Distribution线性光谱分布特性曲

2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package:1000pcs/reel.包装每卷 1000pcs

2.1.1Carrier Tape Dimension 载带尺寸

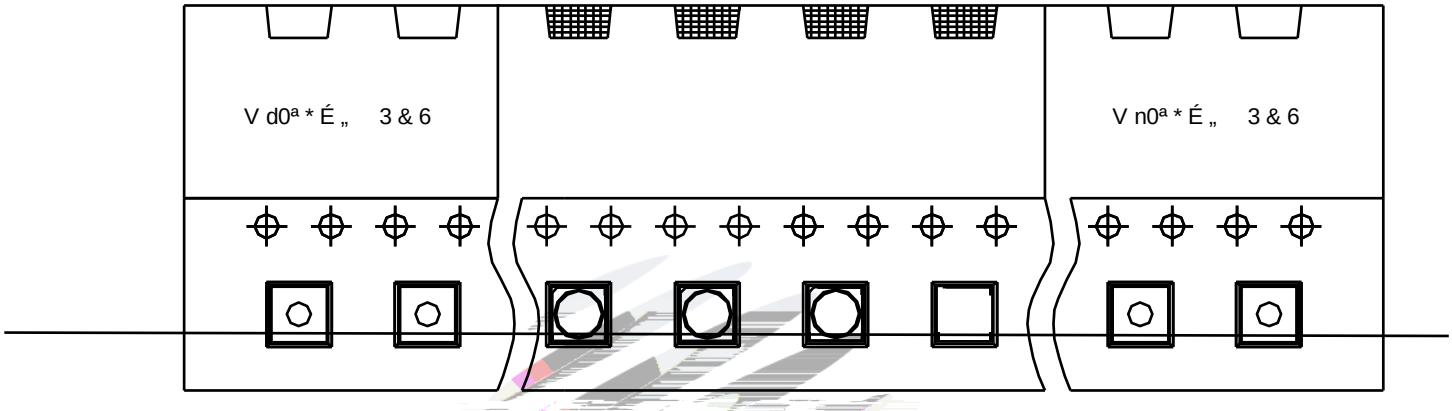


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2Reel Dimension 卷盘尺寸

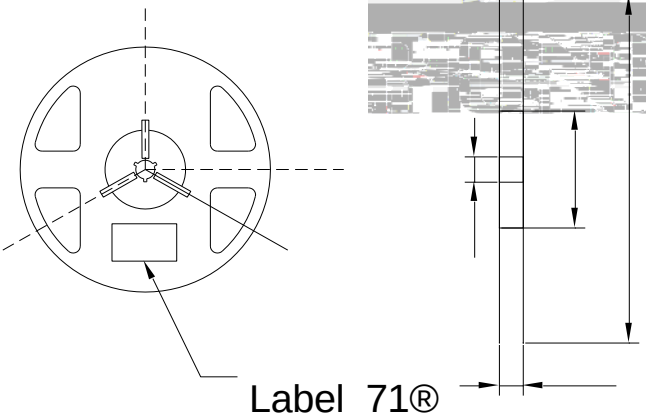


Fig.2-2Reel 卷盘

Table 2-1 Reel Dimension 卷盘尺寸

A	15.8±0.3mm
B	178±1mm
C	59±1mm
D	13.5±0.5mm

Notes 备注：

The tolerances unless mentioned ±0.1mm. Unit : mm ±0.1毫米，尺寸单位：毫米。

2.1.3Label Form Specification 标签规格

Table 2-2 Title

Fig 2-3 Label Form 标签模板

2.2Moisture Resistant Packing 防潮包装

Fig.2-

2.4 Reliability Test Items And Conditions 可靠性测试项目及条件

Table 2-3 Test items and conditions 测试项目及条件

Test Items 项目	Ref. Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	T_{emp}:260°Cmax T=10 sec	2times.	10pcs.	0/1
Thermal Shock 冷热冲击	JEITAED-4701 300307	-40°C 15min 10s 100°C 15min	300 cycle.	10pcs.	0/1
High Temperature Storage 高温保存	JEITAED-4701 200 201	T_{emp}:100°C	1000hrs.	10pcs.	0/1
Low Temperature Storage 低温保存	JEITA ED-4701 200 202	T_{emp}:-40°C	1000hrs.	10pcs.	0/1
Life Test 常温通电	JESD22-A108	T_A=25°C I_F=350mA	1000hrs.	10pcs.	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60°C/ 90%R_H I_F=350mA	500hrs.	10pcs.	0/1

2.5 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria for judging damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	Applicable project 适用项目
Forward Voltage 电压	V_F	I_F=350mA	≤±10%	Reflow

Luminous Flux R	Φ_V	I_F=350mA	Maintenance≥70% 光通量维持率	Thermal Shock High and Low Temperature Storage Life Test
Luminous Flux G			Maintenance≥70% 光通量维持率	
Luminous Flux B			Maintenance≥50% 光通量维持率	
Luminous Flux W			Maintenance≥80% 光通量维持率	
Lamp Bead Light Test 灯珠点亮测试	/	I_F=350mA	No open circuit short circuit or flicke 无开路、短路、闪变	High Temperature High Humidity Life Test

Notes 备注：

1.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.以上可靠性测试是基于固卡实验平台单颗/条 LED 在良好散热条件验证下的结果。客户端将 LED 应用于串、并联线路时，需自行评估电流、电压分配、散热等问题。

2.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。

3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1SMT Reflow Soldering Instructions SMT 回流焊说明

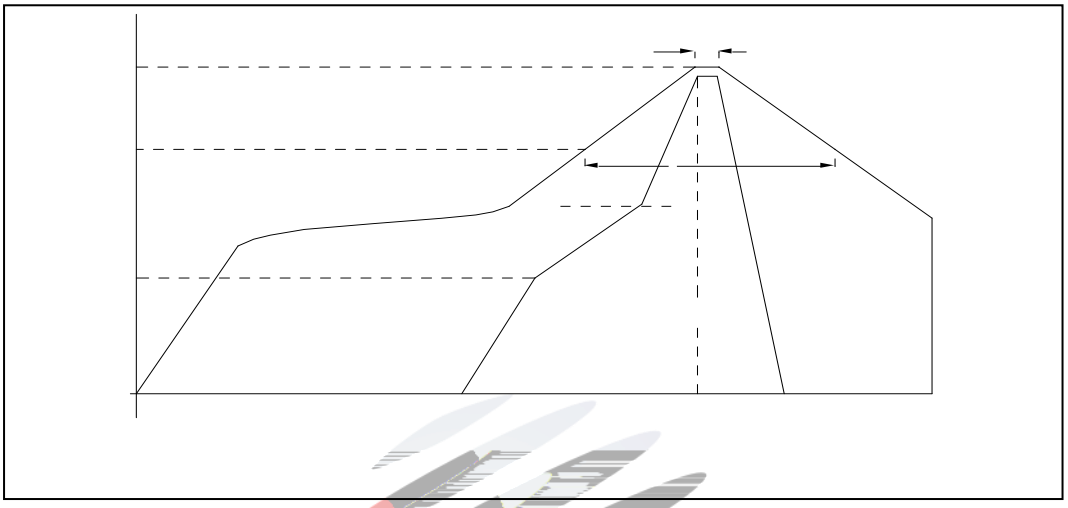


Fig.3-1SMT Reflow Soldering Instructions SMT 回流焊说明

Table 3-1 SMT Reflow Soldering Parameter SMT 回流焊参数

Average temperature rise speed平均升温速度（Tsmax 至T_P）	Max 3 °C/ s 最高3 °C/秒
Preheating: minimum temperature预热：最低温度 (Tsmin)	150 °C
Preheating: Max temperature预热：最高温度 (Tsmax)	200 °C
Preheating: Time预热：时间（Tsmin 至Tsmax）	60 - 120秒 60s-120s
Time limited to maintain high temperature: the temperature限时维持高温：温度 (T_L)	217 °C
Time limited to maintain high temperature: The Time 限时维持高温：时间 (t_L)	Max 60s 最多60秒
Peak /Classification of temperature:峰值 / 分类温度 (T_P)	260 °C
Time limit classification of peak temperature time限时峰值分类温度：时间（t_p）	Max 10s 最多10秒

Hold time within 5 °C with the actual peak temperature (TP) 与实际峰值温度 (T_P) 相差 5 °C 以内的保持时间	Max 30s 最多30秒
Cooling speed 降温速度	Max 6 °C/ s 最高6 °C/秒
Needed time from 25 °C to Tp 25 °C 升至峰值温度所需时间	Max 8 minutes 最多8分钟

Notes 备注:

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 回流焊次数不可以超过两次，两次回流焊的时间间隔如果超过24小时，LED可能由于吸湿而损坏。

(2)Whensoldering , do not put stress on the LEDs during heating.当焊接时，不要在材料受热时用力压胶体表面。

3.1.1 Soldering Iron 烙铁焊接

(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds 当手工焊接时,烙铁的温度必须小于300℃，时间不可超过3秒。

(2) Soldering by hand should be done only one time.手工焊接只可焊接一次。

3.1.2 Repairing 修补

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED回流焊后不应该修复，当必须修复时，必须使用双头烙铁，而且事先应确认此种方式会不会损坏LED本身的特性。

3.1.3 Cautions 注意事项

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when usethe picking up nozzle, the pressure on the silicone resin should be proper. LED封装胶为硅胶，

表面较软，用力按压胶体表面会影响LED可靠性。因此应有预防措施避免在按压器件，当使用吸嘴时，胶体表面的压力应是恰当的。

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED 灯珠不要焊接在弯曲的 PCB 板上，焊接之后，也不要弯折线路板。

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.回流焊之后冷却过程中，不要外力，也不要有震动，回流焊后，不要采后激剧冷却的方式。一要对材料实验

4. Handling Precautions 产品使用注意事项

4.1 Handling Precautions 产品使用注意事项

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM.这只是一个建议，不作任何品质担保。

(2) In order to prevent ex- ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.为了防止外界物质进入 LED 内部以造成 LED 的损伤，所处环境及所用套件等等，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议，不作任何品质担保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific

(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。

Fig 4-1Misoperation 错误操作

(5) In designing a circuit,the current through each LED must be exceed the absolute maximum rating specified for each LED.In the meanwhile,resistors for protection should be applied,otherwise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. 设计电路时，通过 LED 的电流不能超过规定的最大值，同时，还需使用保护电阻，否则，微小的电压变化将会引起较大电流变化，可能导致产品损坏。

变化，不要施加反压，否则会损坏 LED。

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.LED 容易因为自身的发热和环境的温度改变而改变，温度升高会降低 LED 发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring

damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意，当对产品洁净度要求较高时，回流焊以后需要采用恰当的清洗方式，我们推荐用异丙醇作清洗剂，如需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对 LED 带来损害，不推荐这种清洗方式。

Table 4-1Storage 储存

Conditions 种类		Temperature 温度	Humidity 湿度	Time 时间
Storage Øˆ	Before Opening Aluminum Bag 拆包前	≤30℃	≤75%	Within 6 Months From Date 6个月内
	After Opening Aluminum Bag 拆包后	≤30℃	≤60%	168hours 168小时
Baking 烘烤		60±5℃	＜5%	≥24hours 大于24小时

(8) I If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 60 5 and less than 5%RH for above 24 hours.如果干燥剂或包装失效，或者产品不符合储存条件，需拆包后进行烘烤，烘烤条件：60±5℃，小于 5%RH，大于 24 小时。

If the package is flatulence or damaged,please notify the sales staff to assist.如果包装胀气或者破损，请通知销售人员协助处理。

(9)Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 象其他绝大多数固态器件一样，LED 对静电过流击穿非常敏感，需要做好防护。

(10) Other points for attention, please refer to our relevant information.其它注意事项请参照瑞丰相关资料。

Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，若有冲突以中文版本为准。